



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20550	REV: A	SVN REV: Not In VersionControl
	TID #:		
PLOT NAME = Top Assembly Drawing	GENERATED : 1/9/2017	1:50:01 PM	TEXAS INSTRUMENTS

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20550	REV: A	SVN REV: Not In VersionControl
	TID #:		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 1/9/2017	1:50:02 PM	TEXAS INSTRUMENTS

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